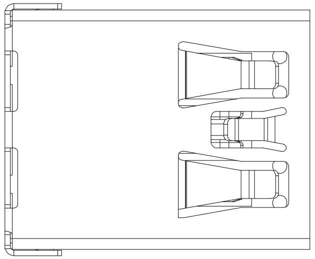
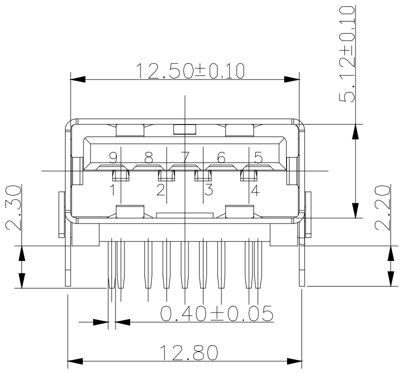
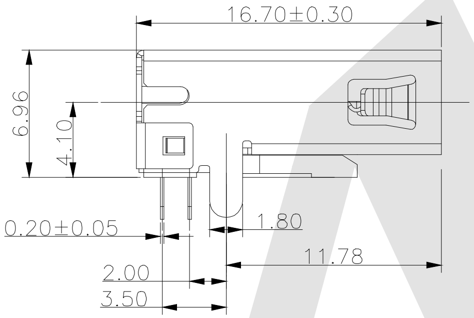
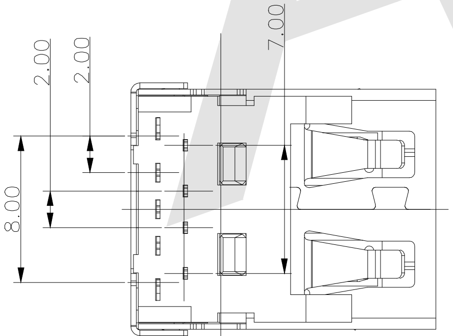
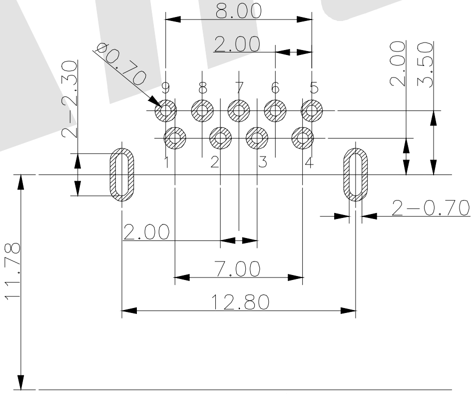
HSF Pb RoHS











RECOMMANDED PCBA LAYOUT
(TOLERANCE+±0.05)

Specifications:

Current Rating:	1.5A Max
Contact Resistance:	50 milliohms MAX
Dielectric Withstanding Voltage:	500V AC AT Sea Levol
Insulation Resistance:	1000 Megaohms MIN

Housing:
Temperature Thermoplastics, PBT UL 94V-0
Contact:
Copper Alloy T=0.20mm Piated Gold in Mating Area;
Tin On Solder Talls
Shell:Iron T=0.30mm Nickel/Plating
Ordering Code:

U3AFR01B - X - P - X - X - X
① ② ③ ④ ⑤ ⑥

①Series No:

②Shell Material:
B:Brass
I:Iron
S:Stainless Steel

③Insulator Material:
P:PBT+30%GF
L:LCP

④Contact Material:
B:Brass
P:phosphor copper

⑤Contact Plating
G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold

⑥ Packing
A:Tray
B:Bag
C:Tube
D:Tape & Reel

REV	DESCRIPTION	DATE

Unless Otherwise specified tolerance
X. ±0.35 X.XX:±0.20
X.X:±0.25 X.XXX:±0.15

SCALE: As Shown	UNIT: mm
DRAW TMX	DATE 10/28/2021
CHECK BobYang	DATE 10/28/2021

3rd ANGLE PROJECTION

Antenk®
ANTENK ELECTRONICS CO,.LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: USB 3.0 AF DIP 90° NO CURLING
DRAWING NO: U3AFR01B-XXXX
PRODUCT NO: U3AFR01B-XXXX